

## GaAs MMIC Monolithic Integrated 0 Degree Power Divider , 2-6 GHz

### Performance characteristics

- Range : 2-6GHz
- Insertion loss : 0.9 dB
- Isolation: 25dB
- Phase imbalance: 2 °
- Amplitude imbalance: 0.1dB
- 50Ohm input / output
- Chip size: QFN 3X3

### Product Introduction

The GPD-0206-CQ3 monolithic integrated 0 - degree power divider has low insertion loss, good isolation, low phase imbalance, low amplitude imbalance and other characteristics in the frequency range of 2 ~ 6 GHz , and is very suitable for microwave hybrid integrated circuits and multi-chip modules. The power divider adopts a 3X3 mm surface-mount leadless ceramic tube shell to achieve airtight packaging, and the surface of the pin pad is gold-plated, which is suitable for reflow soldering installation process.

#### Use restriction parameter <sup>1</sup>

Maximum input power	+40dBm
Operating temperature	-55 ~ +85°C
Storage temperature	-65 ~ +150°C

【1】 Exceeding any of these maximum limits may cause permanent damage.

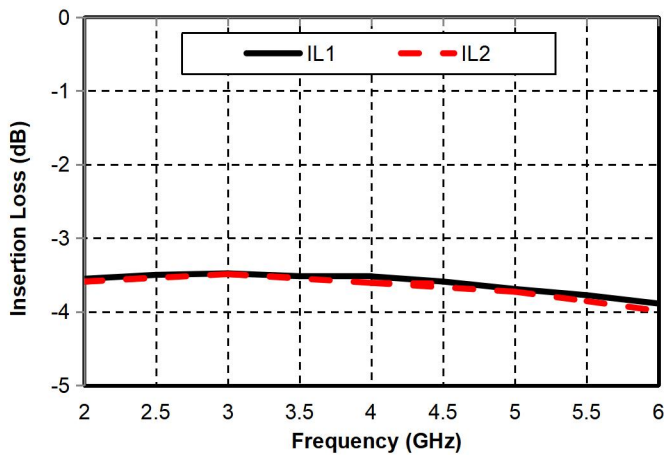
#### Electrical performance parameters ( TA = +25°C)

Index	Minimum	Typical Value	Maximum	Unit
Frequency Range	2-6			GHz
Insertion loss (excluding inherent loss)	-	0.6	-	dB
Insertion loss fluctuation		± 0.2		dB
Isolation	-	25	-	dB
Phase imbalance	-	2	-	degree
Amplitude imbalance	-	0.1	-	dB
Input return loss	-	20	-	dB
Output return loss	-	22	-	dB

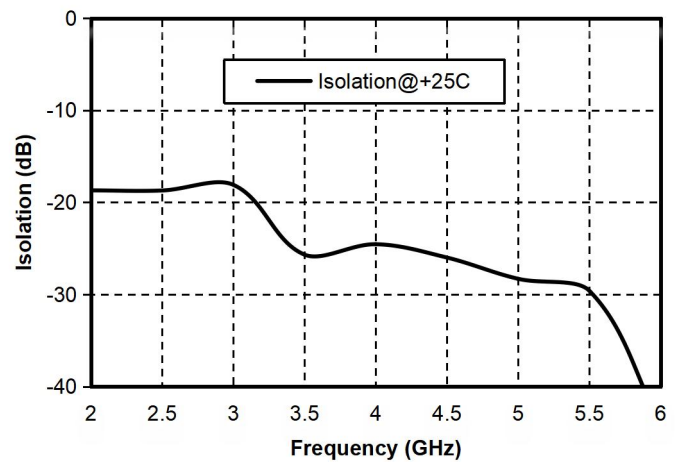
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Main index test curve

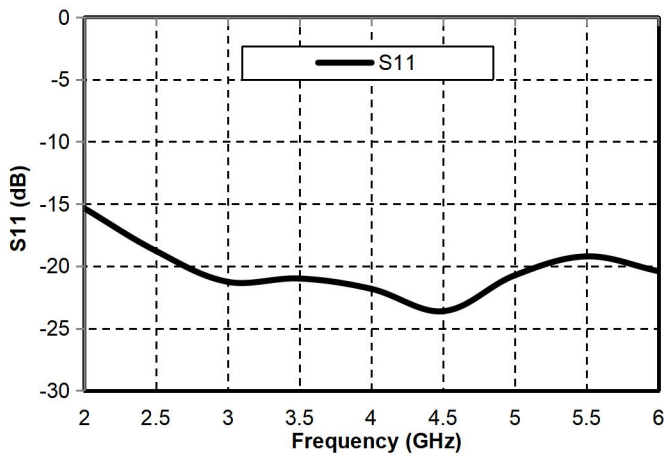
Insertion Loss vs. Operating Frequency



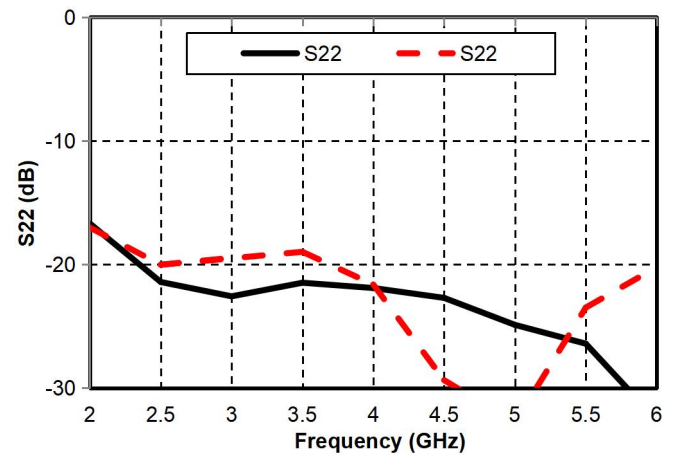
Isolation vs. Operating Frequency



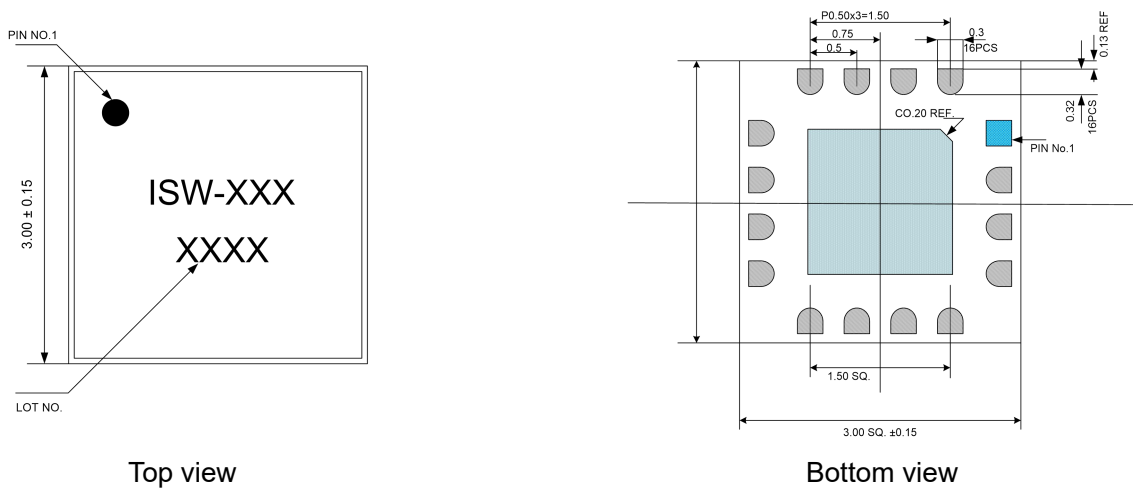
Input Return Loss vs. Operating Frequency



Output Return Loss vs. Operating Frequency

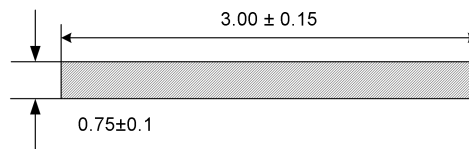


Appearance structure



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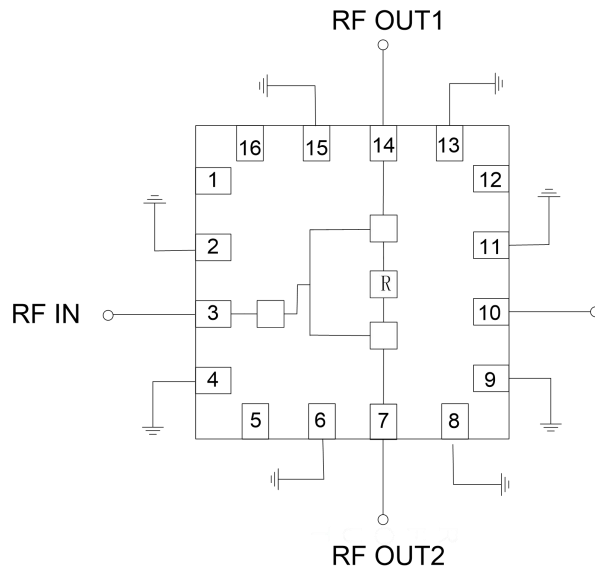


Side View

All units in the figures are millimeters .

Pin Definition		
Solder point number	Function Symbol	Functional Description
3	RFIN	RF signal input terminal
7 , 14	RFOUT1 , RFOUT2	RF signal output terminal
2 , 4 , 6 , 8 , 13 , 15	GND	The bottom of the chip needs to be well grounded to RF and DC
Other	NC	No welding required

### Recommended assembly drawing



## Precautions for use

- Sealing material : Ceramic material that meets ROHS standards
- Lead frame material: copper alloy
- Lead surface plating: gold, gold layer thickness 0.3um MIN
- Maximum reflow peak temperature: 260 °C